

## CLAIMS

What is claimed is:

1. A digital image capturing module assembly, which comprises:

a lens holder, which has one side defined as a focusing plane, and which is formed  
5 with a shouldered portion on the lens holder's inner wall on the periphery of the focusing  
plane and is further formed with a grooved portion in the shouldered portion;

an adhesive layer, which is coated in the grooved portion in the shouldered portion  
of the lens holder; and

a photosensitive printed circuit board, which is embedded in the space confined  
10 within the lens holder's inner wall over the shouldered portion, and which is adhered by  
means of the adhesive layer to the lens holder so as to be fixedly mounted on the lens holder  
with a sealed light-impenetrable quality at the junction between the photosensitive printed  
circuit board and the lens holder.

2. The digital image capturing module assembly of claim 1, wherein the  
15 photosensitive printed circuit board is a CCD-based photosensitive printed circuit board.

3. The digital image capturing module assembly of claim 1, wherein the  
photosensitive printed circuit board is a CMOS-based photosensitive printed circuit board.

4. The digital image capturing module assembly of claim 1, wherein the shouldered  
portion is dimensioned to a depth substantially equal to the thickness of the photosensitive  
20 printed circuit board.

5. The digital image capturing module assembly of claim 1, wherein the space  
confined within the lens holder's inner wall on the shouldered portion is dimensioned to be  
substantially equal to the area of the photosensitive printed circuit board.

6. A method for fabricating a digital image capturing module, comprising:

preparing a lens holder having one side defined as a focusing plane, and which is formed with a shouldered portion on the lens holder's inner wall on the periphery of the focusing plane and is further formed with a grooved portion in the shouldered portion;

5 preparing a photosensitive printed circuit board;

coating an adhesive layer in the grooved portion in the shouldered portion of the lens holder; and

embedding the photosensitive printed circuit board in the space confined within the lens holder's inner wall over the shouldered portion, and which is adhered by means of the adhesive layer to the lens holder so as to be fixedly mounted on the lens holder with a sealed light-impenetrable quality at the junction between the photosensitive printed circuit board and the lens holder.

7. The method of claim 6, wherein the photosensitive printed circuit board is a CCD-based photosensitive printed circuit board.

15 8. The method of claim 6, wherein the photosensitive printed circuit board is a CMOS-based photosensitive printed circuit board.

9. The method of claim 6, wherein the shouldered portion is dimensioned to a depth substantially equal to the thickness of the photosensitive printed circuit board.

10. The method of claim 6, wherein the space confined within the lens holder's inner wall on the shouldered portion is dimensioned to be substantially equal to the area of the photosensitive printed circuit board.

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